

SOT638-5

plastic thermal enhanced thin quad flat package; 100 leads;
body 14 x 14 x 1 mm; exposed die pad

10 February 2016

Package information

1. Package summary

| | |
|---------------------------------------|---|
| Terminal position code | Q (quad) |
| Package type descriptive code | HTQFP100 |
| Package type industry code | HTQFP100 |
| Package style descriptive code | HTQFP (thermal enhanced thin quad flat package) |
| Package style suffix code | NA (not applicable) |
| Package body material type | P (plastic) |
| JEDEC package outline code | MS-026 |
| Mounting method type | S (surface mount) |
| Issue date | 12-11-2008 |

Table 1. Package summary

| Symbol | Parameter | Min | Typ | Nom | Max | Unit |
|----------------|--------------------------------|------|-----|-----|------|------|
| D | package length | 13.9 | - | 14 | 14.1 | mm |
| E | package width | 13.9 | - | 14 | 14.1 | mm |
| A | seated height | 0.95 | - | 1 | 1.2 | mm |
| A ₂ | package height | 0.95 | - | 1 | 1.05 | mm |
| n ₂ | actual quantity of termination | - | - | 100 | - | |



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2. Legal information

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